

MARKED UP VERSION OF REWRITTEN CLAIMS

20. (Amended) A semiconductor device according to claim 1 [or claim 19], wherein the semiconductor element fixing area is smaller than the semiconductor element.

31. (Amended) A semiconductor device according to [any of] claim[s] 1, [13, 14 and 26,] wherein the tab, the tab suspension leads, and the plural leads are each formed of a metal.

32. (Amended) A semiconductor device according to [any of] claim[s] 1, [13, 14 and 26,] wherein the tab, suspension leads, and the plural leads are all formed of one and same metallic material.

33. (Amended) A semiconductor device according to [any one of] claim[s] 1, [13, 14, and 26,] wherein the plural leads are arranged around the tab and a space between the leads and the tab is filled with the seal member.

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